



SPEC NO.: SSR-109M

SPECIFICATION

TO:

Model Name: SAW RESONATOR **PART NO: SSR315N01S5035** CUSTOMER PART NO.:

Approval Sheet:

	Yes
Approved	No.
Customer's comments are welcomed here.	
Pls return this copy as a certificate of your approval by email.	
Approved By Date:	

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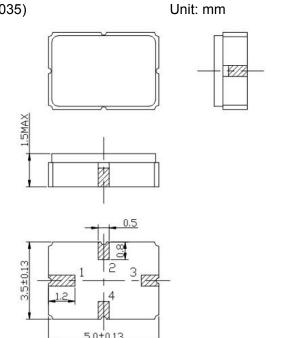
History Record

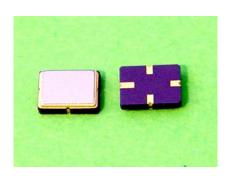
Date	Part No.	SPEC No.	Description.	Remarks.
		Annroyed by	Chook by	Dosign by
RoHS Compliant	ISO9001:2000	Approved by	Check by	Design by
Lead free Clearing	ISO14001:2004	June-2-2009	June-2-2009	May-31-2009
Reversions	Total Page	Xu gang dong	Liu jun	Wang hon



1. Package Dimension

(S5035)





Pin No.	Function
Pin 2	Input
Pin 4	Output
Others	Ground

2. Marking

R

(1) Ink Marking or Laser Marking

3001

(2) R: STRONG LOGO (3) 3001: Model code

(4) .: Pin 1 Identifier

• AH6

(5) R01: Tolerance code (+/-100KHz)

6

(6) H6: Date code

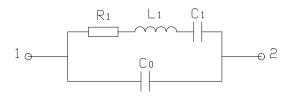
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Month code						Las	t figu	ire of	f yeaı	٢			
Month		1	2	3	4	5	6	7	8	9	10	11	12
Month code		Α	В	С	D	Е	F	G	Н	I	J	K	L

e.g.: "H6" means August of 2006

3. Equivalent LC Model





4. Performance

4.1 Maximum Rating

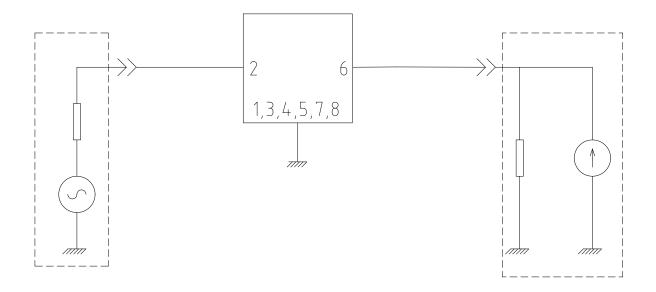
item:	
Operation Temperature Range	-40℃ to +80℃
Storage Temperature Range	-45℃ to +85℃
DC Voltage	10V
Source Power	0 dBm

4.2 Electronic Characteristics

ltem	Units	Minimum	Typical	Maximum	
Center Frequency (fo)	MHz	314.925	315	315.075	
Insertion Loss	dB	_	1.5	2.0	
Quality Factor					
Unloaded Q	_	_	11,000	_	
50Ω Loaded Q		_	2,000	<u> </u>	
Temperature Stability					
Turnover Temperature	$^{\circ}$ C	C _ 25		_	
Freq. Temp. Coefficient	ppm/℃	_	0.032	_	
Frequency Aging	ppm/yr	_	<±10	_	
DC Insulation Resistance	ΜΩ	1.0	_	_	
RF Equivalent RLC Model					
Motional Resistance R1	Ω	_	18	26	
Motional Inductance L1	μH	_	86	_	
Motional Capacitance C1	fF	_	1.56	_	
Shunt Static Capacitance C0	pF	1.7	2.0	2.3	

4.3 Test Circuit





5. Reliability

5.1 Resistance to Soldering heat:

- 5.1.1 The components shall remain within the electrical specifications after it soldered on the 1mm-thickness PCB board and dipped in the solder at 260 ℃ ±5 ℃ for 10±1 seconds.
- 5.1.2 The components shall remain within the electrical specifications after it soldered by electric iron, solder at 350° C±10°C for 3~4 seconds, recovery time : 2h±0.5h.

5.2 Thermal Shock:

The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40 $^{\circ}$ C±3 $^{\circ}$ C, TB=85 $^{\circ}$ C±2 $^{\circ}$ C, t1=t2=30min, switch time≤3min & cycle time : 100 times, recovery time : 2h±0.5h.

5.3 The Temperature Storage:

- 5.3.1 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the $85^{\circ}\pm2^{\circ}$ for 500 hours, recovery time : $2h\pm0.5h$.
- 5.3.2 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the $-40^{\circ}\pm3^{\circ}$ for 500 hours, recovery time : 2h±0.5h.

5.4 Humidity test:

The components shall remain within the electrical specifications after being kept at the condition of ambient temperature $60^{\circ}\text{C}\pm2^{\circ}\text{C}$, and $90\sim95\%$ RH for 500 hours.

5.5 Drop test:

The components shall remain within the electrical specifications after random free drops 10 times from height of 1.0 meter onto concrete floor, and the specimens shall meet the electrical



specifications in table 5, external visual inspection.

5.6 Solderability test:

at the condition of temperature 245 $^{\circ}$ C ± 5 $^{\circ}$ C Depth: DIP 2/3 , SMD 1/5, time: 3.0s-5.0s, 80% or more of the immersed surface shall be covered with solder and well-proportioned.

5.7 Vibration Fatigue:

The components shall remain within the electrical specifications after loaded vibration at 10~55Hz, amplitude 1.5mm, X, Y, Z, direction, for 2 hours.

5.8Terminal strength:

The force 10±1 seconds of 19.6N is applied to each terminal, and 45° in the same direction 2 times with 2N bending force (Exception: SMD)

5.9 Mechanical Shock:

The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s^2 , duration 6ms.

6. Remarks

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

7.Packing



7.1 Dimensions

Carrier Tape: Figure 1

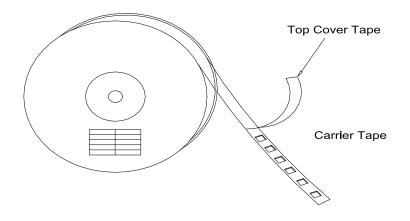
Reel: Figure 2

The product shall be packed properly not to be damaged during transportation and storage.

7.2 Reeling Quantity 1,000 pcs/reel

7.3 Taping Structure

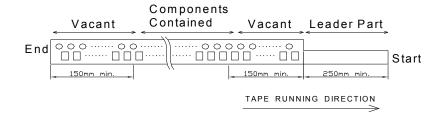
(1) The tape shall be wound around the reel in the direction shown below.



(2) Labe 1

Device Name	
Type	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.



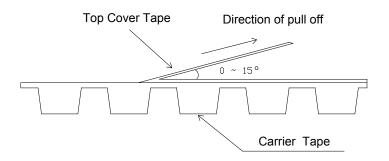
8. Tape Specifications

8.1 Tensile Strength of Carrier Tape: 4.4N/mm width

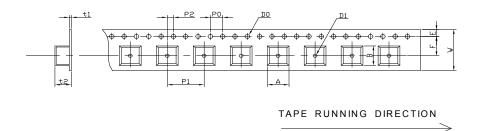


8.2 Top Cover Tape Adhesion (See the below figure)

(1) pull off angle: 0~15°(2) speed: 300mm/min.(3) force: 20~70g



[Figure 1] Carrier Tape Dimensions



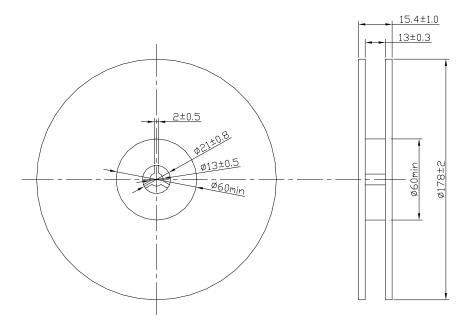
[Unit: mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	А	В
12.0	5.5	1.75	4.0	8.0	2.0	Ф1.5	Ф1.5	0.31	1.95	5.5	5.5
±0.3	±0.1	±0.1	±0.2	±0.1	±0.2	±0.1	±0.25	max.	max.	max.	max.

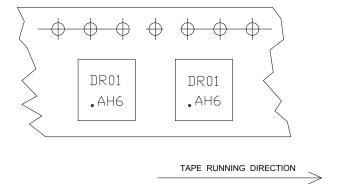
[Figure 2] Reel Dimensions

[Unit: mm]





[Figure 3] Part Direction



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